

Application No.: 10/055,568

Docket No.: JCLA8533

REMARKS

1. Present Status of the Application

Upon this response, claims 168-218 remain pending in the present application. More specifically, claims 1-167 are canceled; claims 168-218 are newly added. It is believed that the foregoing amendments add no new matter to the present application.

2. Response To Objections/Rejections

Applicants respectfully traverse the rejections for at least the reasons set forth below.

Response To Claim 168

As amended, independent claim 168 is recited below:

*168. A chip package structure comprising:
a preformed substrate comprising semiconductor material, said preformed substrate having no circuitry;
only one preformed die joined with said preformed substrate; and
a metal layer over said only one preformed die.*

Applicants respectfully assert that the chip package claimed in claim 168 patentably distinguishes over the citations by Maruyama, by Hozoji, by Sakai and by Gonzalez.

Maruyama (US2001/0042901) teaches a semiconductor wafer 11 provided with multiple circuit regions 12. ~ See FIGS. 17A-17D and paragraph [0083] ~ Maruyama fails to teach the circuit regions 12 can be preformed. However, applicants teach a die can be preformed and the preformed die can be joined with a preformed substrate comprising semiconductor material, which is not taught by Maruyama.

Hozoji (US2002/0079575) teaches a preformed die 1 can be joined with a preformed substrate having multiple circuit layers 8 and 31. ~ See FIG. 7 ~ Hozoji fails to teach the

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performed die 1 can be joined with a preformed substrate having no circuitry. However, applicants teach a preformed die can be joined with a preformed substrate having no circuitry, which is not taught by Hozoji.

For at least the foregoing reasons, applicants respectfully submit independent claim 168 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 169-218 patently define over the prior art as well. In addition, these dependent claims contain features that further distinguish over the cited references.

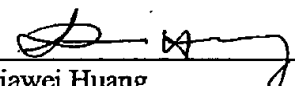
CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 168-218 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,
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